

## N-Channel 80 V (D-S) MOSFET

PRODUCT SUMMARY			
$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ ) Max.	$I_D$ (A) <sup>a</sup>	$Q_g$ (Typ.)
80	0.093 at $V_{GS} = 10$ V	4.6	2.6
	0.108 at $V_{GS} = 6$ V	4.3	
	0.126 at $V_{GS} = 4.5$ V	4	

### FEATURES

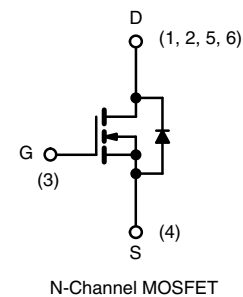
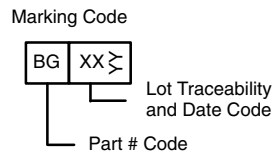
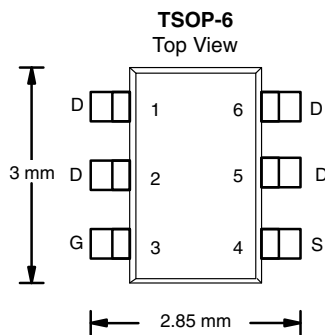
- TrenchFET<sup>®</sup> Power MOSFET
- 100 %  $R_g$  Tested
- Material categorization:  
For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Load Switch for Portable Applications
- LED Backlight Switch
- DC/DC Converter
- Boost Converter



Ordering Information: Si3476DV-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C, unless otherwise noted)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	80	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current ( $T_J = 150$ °C)	$I_D$	$T_C = 25$ °C	4.6
		$T_C = 70$ °C	3.7
		$T_A = 25$ °C	3.5 <sup>b,c</sup>
		$T_A = 70$ °C	2.8 <sup>b,c</sup>
Pulsed Drain Current ( $t = 100$ $\mu$ s)	$I_{DM}$	18	A
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25$ °C	
		$T_A = 25$ °C	1.7 <sup>b,c</sup>
Maximum Power Dissipation	$P_D$	$T_C = 25$ °C	3.6
		$T_C = 70$ °C	2.3
		$T_A = 25$ °C	2 <sup>b,c</sup>
		$T_A = 70$ °C	1.3 <sup>b,c</sup>
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 150	°C

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b,d</sup>	$R_{thJA}$	50	62.5	°C/W
Maximum Junction-to-Foot (Drain)	$R_{thJF}$	28	35	

#### Notes:

- Based on  $T_C = 25$  °C.
- Surface mounted on 1" x 1" FR4 board.
- $t = 5$  s.
- Maximum under steady state conditions is 110 °C/W.

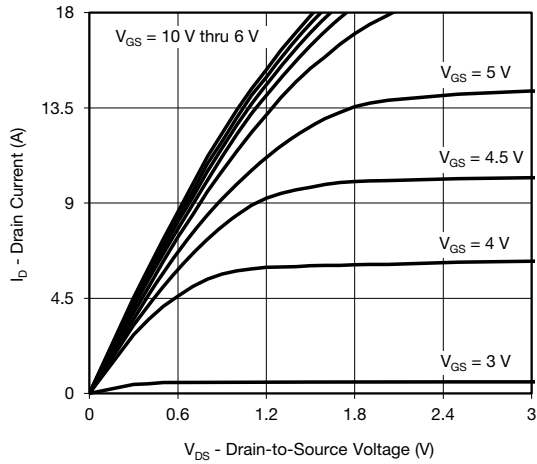
<b>SPECIFICATIONS</b> ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	80			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		36		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 4.8		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1.2		3	V
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}, T_J = 85\text{ }^\circ\text{C}$			10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	10			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 3.5\text{ A}$		0.077	0.093	$\Omega$
		$V_{GS} = 6\text{ V}, I_D = 3.2\text{ A}$		0.090	0.108	
		$V_{GS} = 4.5\text{ V}, I_D = 3\text{ A}$		0.105	0.126	
Forward Transconductance	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 3.5\text{ A}$		7		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		195		pF
Output Capacitance	$C_{oss}$			116		
Reverse Transfer Capacitance	$C_{rss}$			16		
Total Gate Charge	$Q_g$	$V_{DS} = 40\text{ V}, V_{GS} = 10\text{ V}, I_D = 3.5\text{ A}$		4.9	7.5	nC
				2.6	5	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 40\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 3.5\text{ A}$		0.8		
Gate-Drain Charge	$Q_{gd}$			1.3		
Gate Resistance	$R_g$	$f = 1\text{ MHz}$	0.82	4.2	8.2	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 40\text{ V}, R_L = 14.3\text{ }\Omega$ $I_D \cong 2.8\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		8	16	ns
Rise Time	$t_r$			4	8	
Turn-Off Delay Time	$t_{d(off)}$			14	21	
Fall Time	$t_f$			3	6	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 40\text{ V}, R_L = 14.3\text{ }\Omega$ $I_D \cong 2.8\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 1\text{ }\Omega$		26	40	
Rise Time	$t_r$			50	75	
Turn-Off Delay Time	$t_{d(off)}$			12	20	
Fall Time	$t_f$			15	23	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$			3	A
Pulse Diode Forward Current ( $t = 100\text{ }\mu\text{s}$ )	$I_{SM}$				18	
Body Diode Voltage	$V_{SD}$	$I_S = 2.8\text{ A}$		0.85	1.2	V
Body Diode Reverse Recovery Charge	$Q_{rr}$	$I_F = 2.8\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		13	20	nC
Body Diode Reverse Recovery Time	$t_{rr}$			20	30	ns
Reverse Recovery Fall Time	$t_a$			10.5		
Reverse Recovery Rise Time	$t_b$			9.5		

**Notes:**

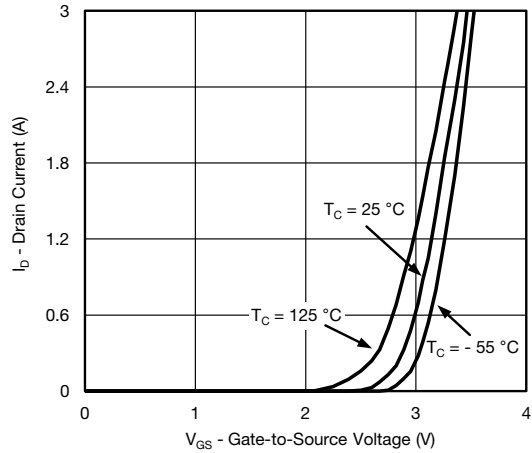
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

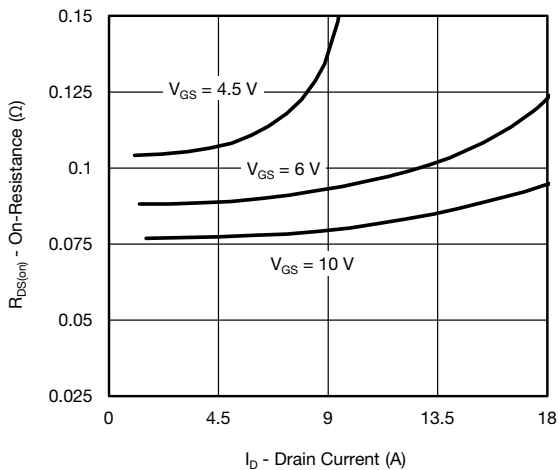
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



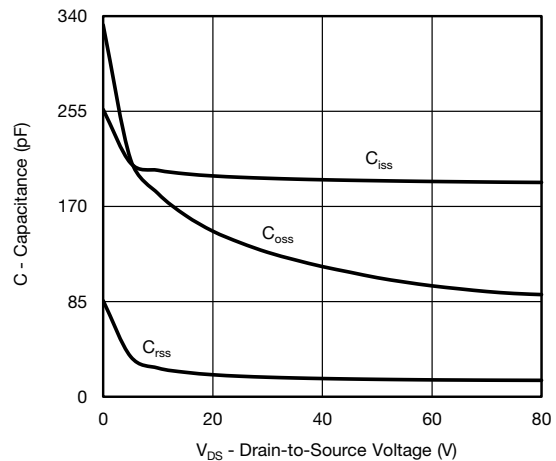
**Output Characteristics**



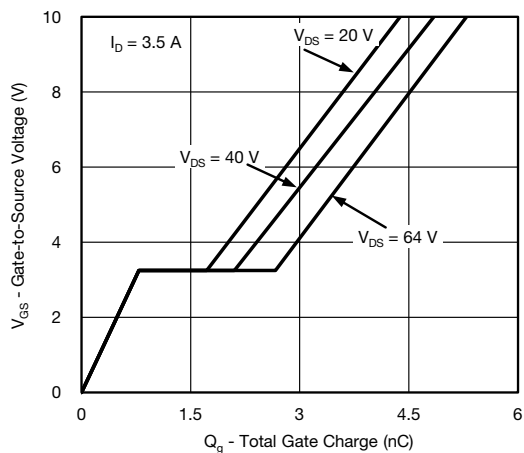
**Transfer Characteristics Curves vs. Temp.**



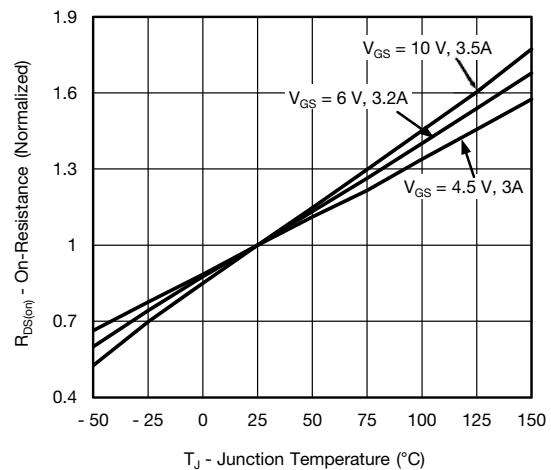
**On-Resistance vs. Drain Current**



**Capacitance**

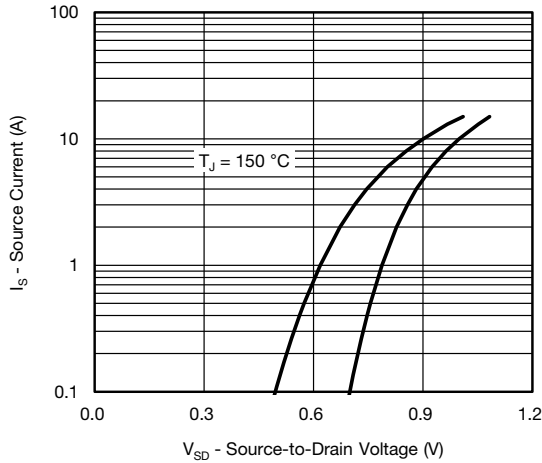


**Gate Charge**

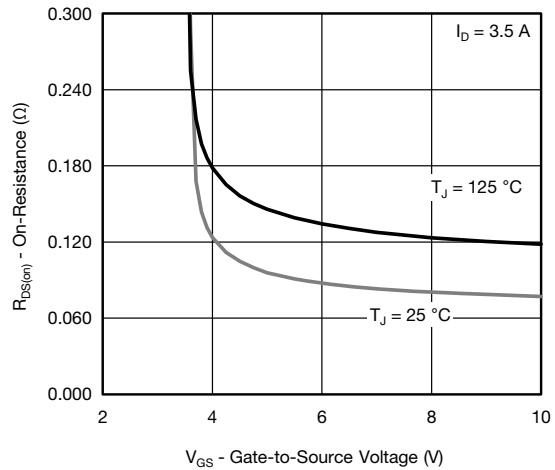


**On-Resistance vs. Junction Temperature**

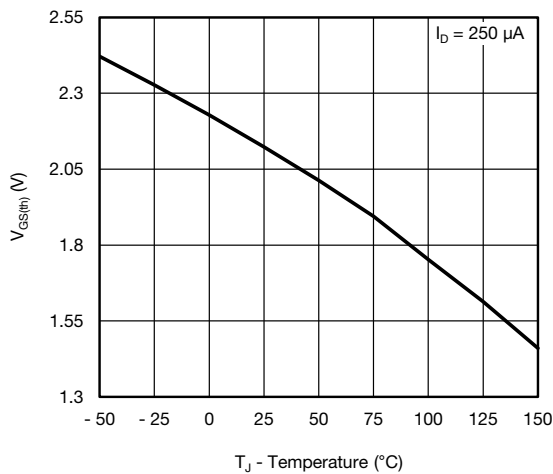
## TYPICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



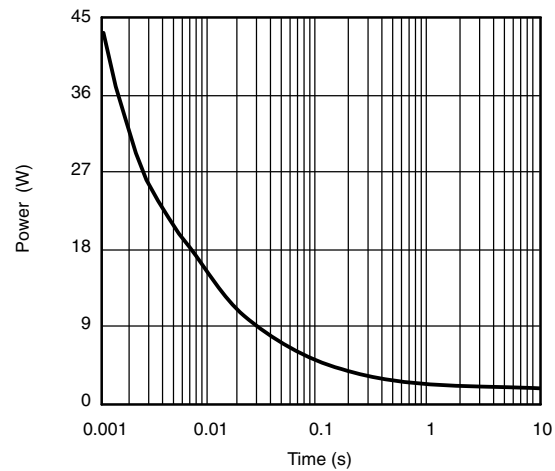
Source-Drain Diode Forward Voltage



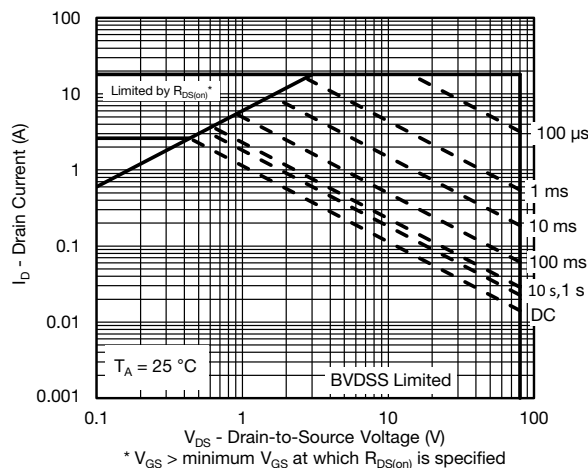
$R_{DS(on)}$  vs.  $V_{GS}$  vs. Temperature



Threshold Voltage

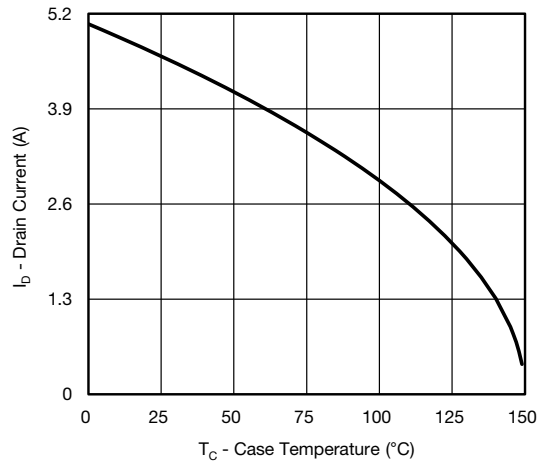


Single Pulse Power (Junction-to-Ambient)

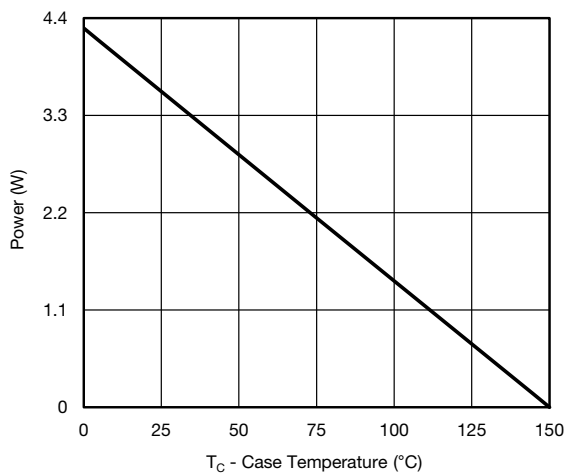


Safe Operating Area, Junction-to-Ambient

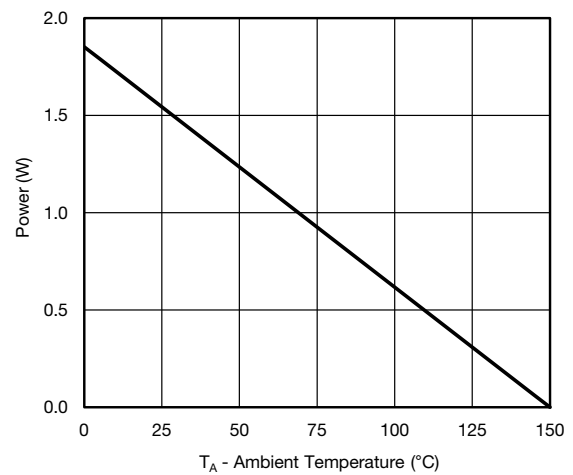
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Current Derating\***



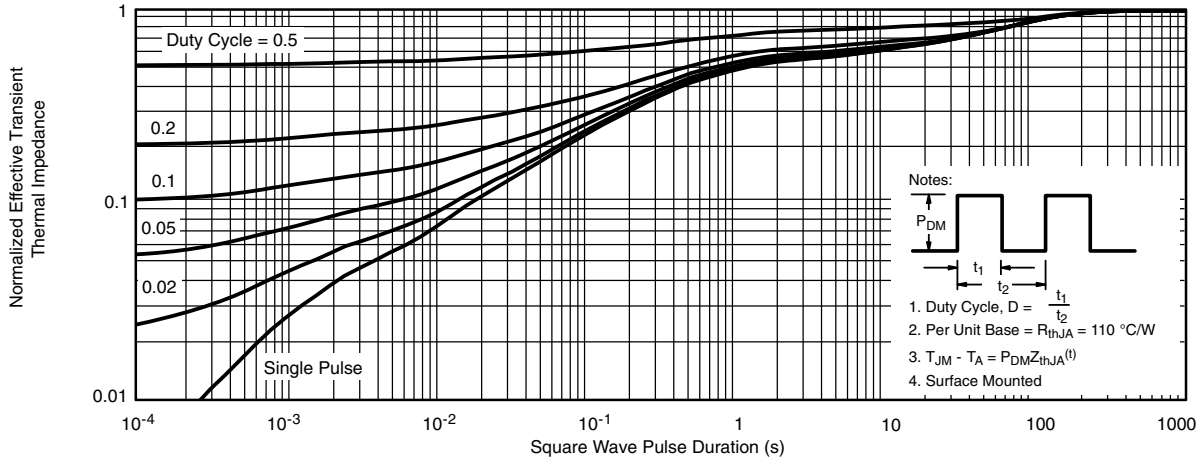
**Power Derating, Junction-to-Foot**



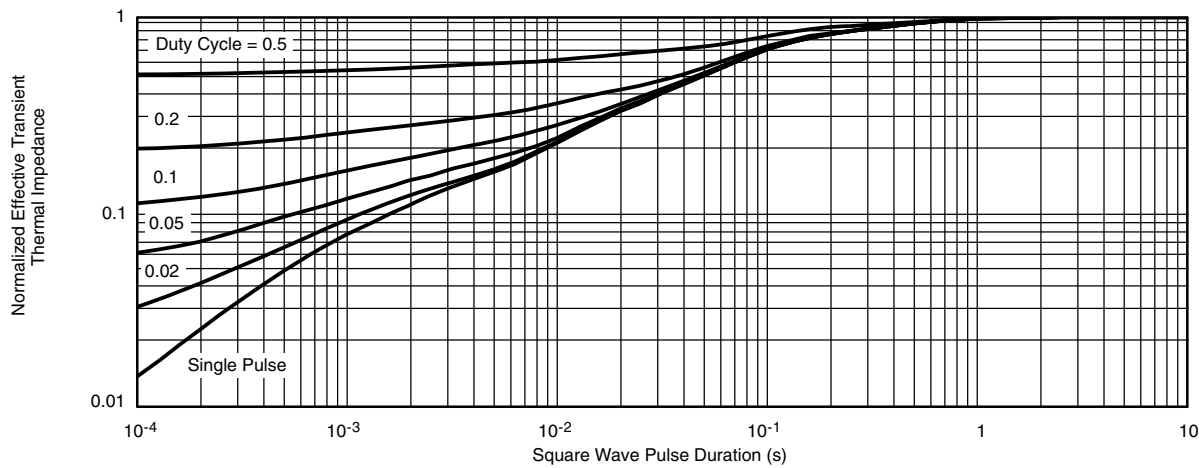
**Power Derating, Junction-to-Ambient**

\* The power dissipation  $P_D$  is based on  $T_{J(max.)} = 150\text{ }^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**Normalized Thermal Transient Impedance, Junction-to-Foot**

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## TSOP: 5/6-LEAD

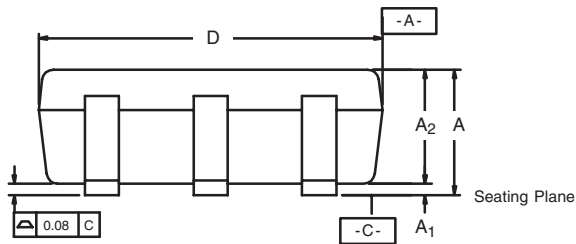
JEDEC Part Number: MO-193C



5-LEAD TSOP



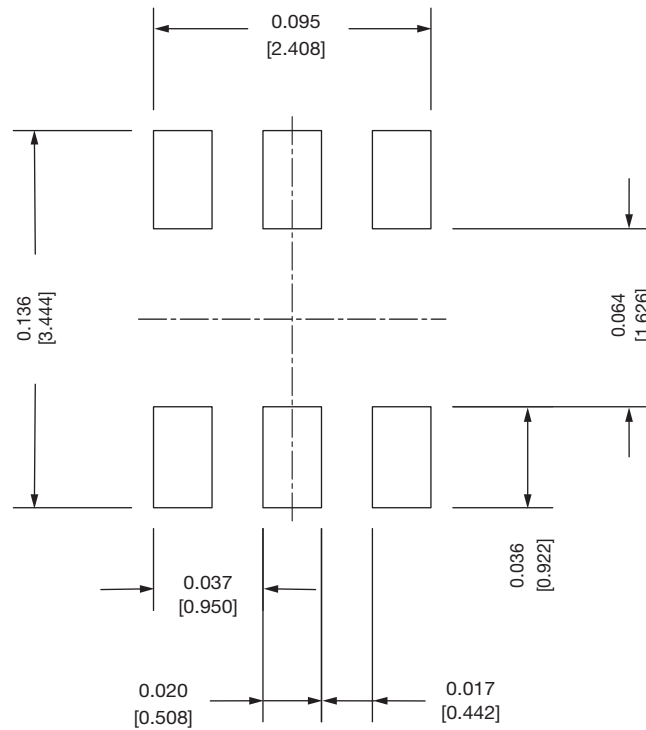
6-LEAD TSOP



Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
<b>A</b>	0.91	-	1.10	0.036	-	0.043
<b>A<sub>1</sub></b>	0.01	-	0.10	0.0004	-	0.004
<b>A<sub>2</sub></b>	0.90	-	1.00	0.035	0.038	0.039
<b>b</b>	0.30	0.32	0.45	0.012	0.013	0.018
<b>c</b>	0.10	0.15	0.20	0.004	0.006	0.008
<b>D</b>	2.95	3.05	3.10	0.116	0.120	0.122
<b>E</b>	2.70	2.85	2.98	0.106	0.112	0.117
<b>E<sub>1</sub></b>	1.55	1.65	1.70	0.061	0.065	0.067
<b>e</b>	0.95 BSC			0.0374 BSC		
<b>e<sub>1</sub></b>	1.80	1.90	2.00	0.071	0.075	0.079
<b>L</b>	0.32	-	0.50	0.012	-	0.020
<b>L<sub>1</sub></b>	0.60 Ref			0.024 Ref		
<b>L<sub>2</sub></b>	0.25 BSC			0.010 BSC		
<b>R</b>	0.10	-	-	0.004	-	-
<b>θ</b>	0°	4°	8°	0°	4°	8°
<b>θ<sub>1</sub></b>	7° Nom			7° Nom		
ECN: C-06593-Rev. I, 18-Dec-06						
DWG: 5540						



# Recommended Land Pattern For TSOP-5L / TSOP-6L



**Note**

- All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022  
 DWG: 3010





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